

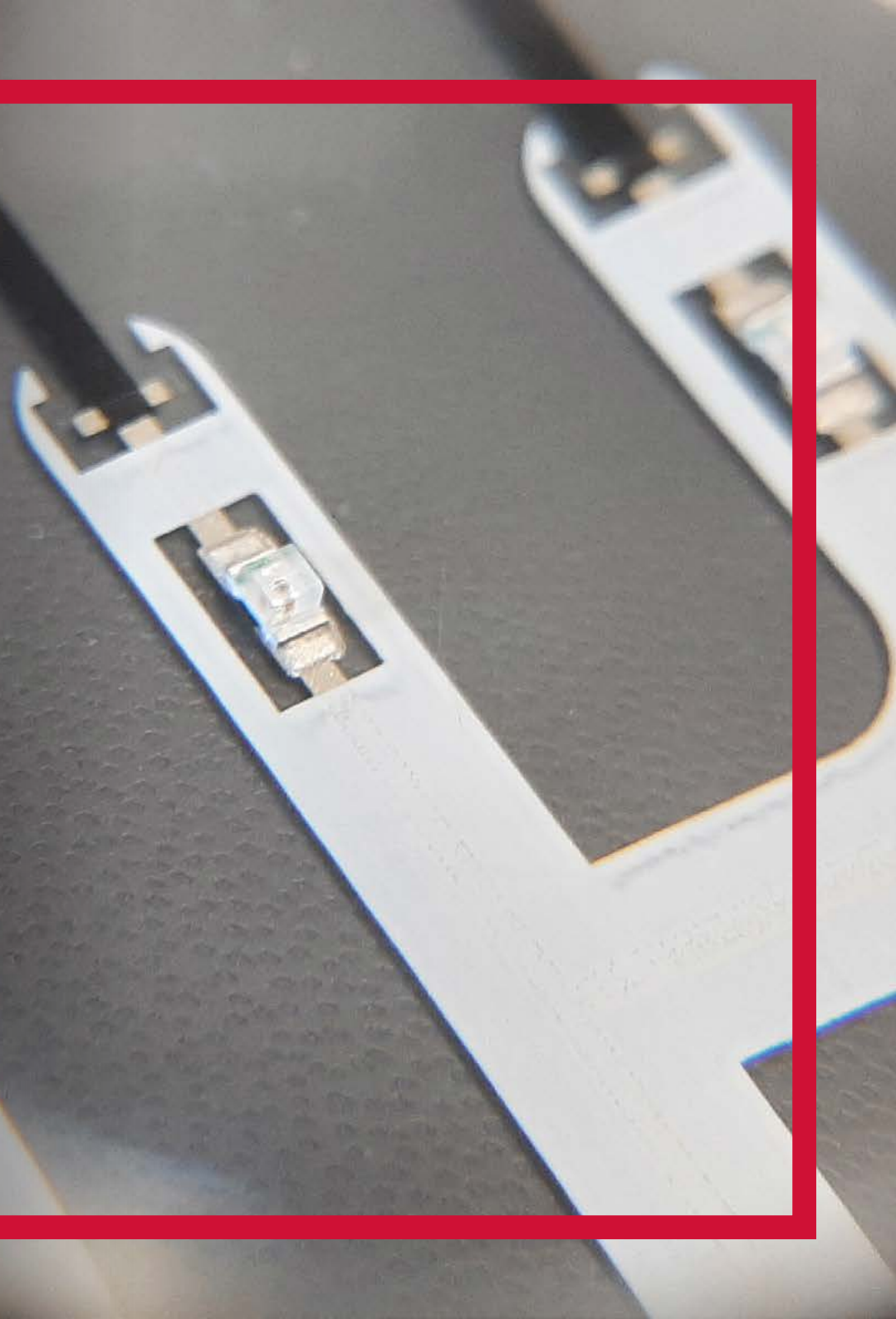
# ELECTRICALLY CONDUCTIVE ADHESIVES

(ECAs)

SMD attach, EMI shielding  
and solder replacement

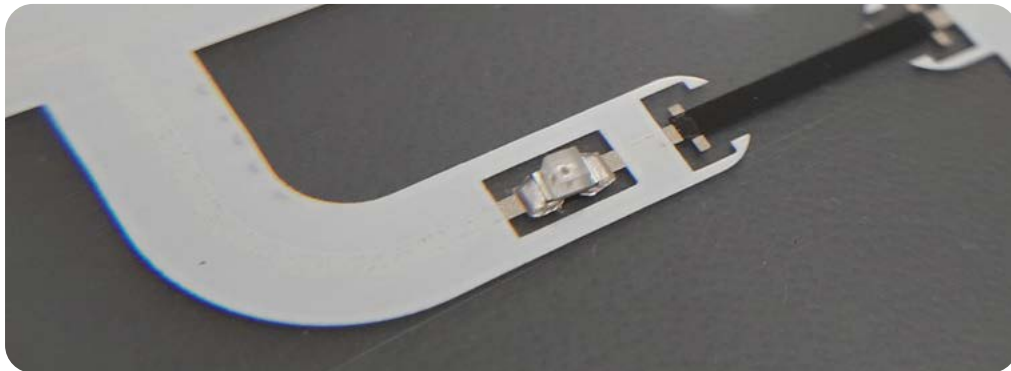
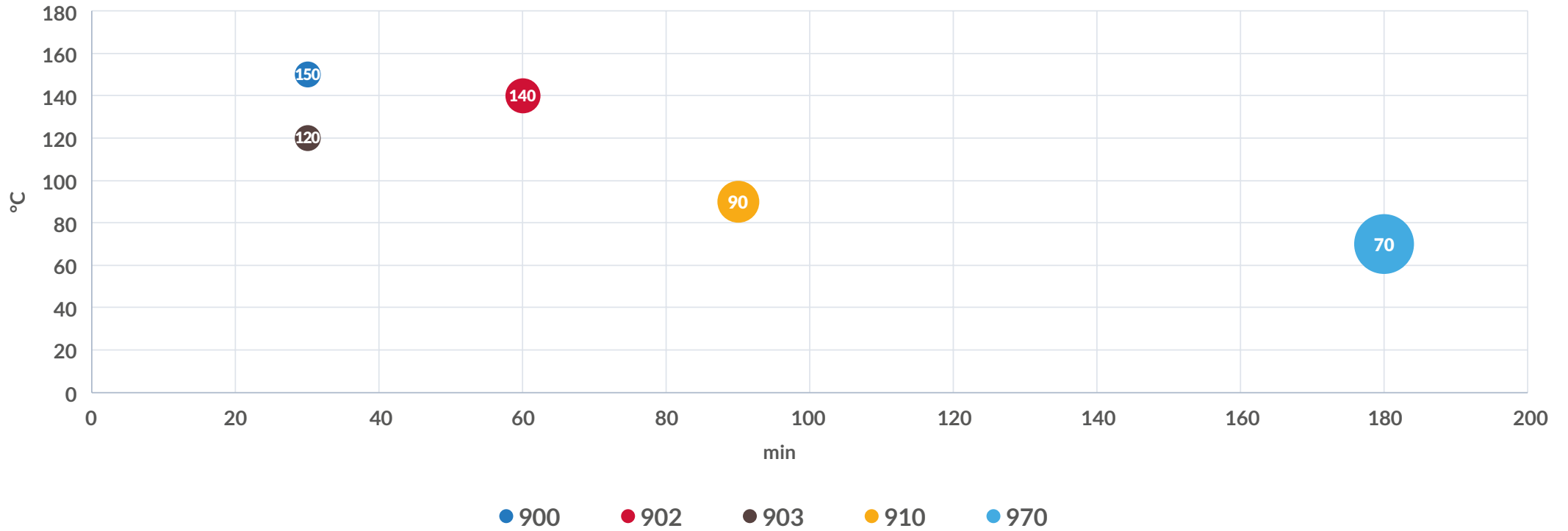
# SILVER FILLED EPOXY ADHESIVES

\*refer to data sheets for complete informations



	Solid Content, %	Best Curing Conditions, Time & Temperature	Deposition	Volume Resistance, $\Omega \cdot \text{Cm}$	Solventless	Substrate	Best Storage Conditions
<p><b>Ag PASTE 670 EI</b></p> <p>Two component adhesive for mounting electronic components on printed circuits - Polymerization is completed at very low temperature even at room temperature (48 hours) - BENEFIT: provide a certain flexibility when fully cured.</p>	> 90	180'@70°C	Volumetric dosing dispensing	< 10 <sup>-3</sup>	NO	T. sensitive, flexible	12 months @4°-10°C for unmixed system
<p><b>Ag PASTE 900 EI</b></p> <p>One component screen printable paste for through hole or heating elements - Polymerization is completed at 150°C (minimum T) - BENEFIT: superior adhesion and abrasion resistance.</p>	< 80	30'@150°C	Screen printing, stencil	< 10 <sup>-4</sup>	NO	Rigid only	12 months @4°-10°C
<p><b>Ag PASTE 902 EI</b></p> <p>One component dispensable adhesive for mounting electronic components on printed circuits - Polymerization is completed at 150°C (minimum T) - BENEFIT: high adhesion and electrical conductivity.</p>	< 75	60'@140°C	Screen printing, stencil or dispensing	< 10 <sup>-4</sup>	NO	Rigid or flex	12 months @4°-10°C
<p><b>Ag PASTE 903 EI</b></p> <p>One component dispensable adhesive designed for IME - Polymerization is completed at 80°C (minimum T) - BENEFIT: high degree of compatibility with underprinted inks.</p>	> 98	30'@120°C	Stencil, volumetric dosing dispensing	< 10 <sup>-4</sup>	YES	T. sensitive, flexible	12 months @4°-10°C
<p><b>Ag PASTE 910 EI</b></p> <p>One component dispensable adhesive for mounting electronic components on printed circuits - Polymerization is completed at 80°C (minimum T) - BENEFIT: high electrical conductivity.</p>	> 90	90'@90°C	Stencil, volumetric dosing dispensing	< 10 <sup>-4</sup>	NO	T. sensitive, flexible	6 months @4°-10°C

# BEST CURING CONDITIONS



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